Vincotech

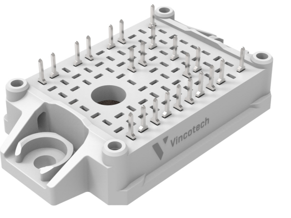
10-E112PMA015M701-L928A73Z
datasheet

***flow*PIM E1** **1200 V / 15 A**

Topology features

- Common brake+Inverter DC+
- Converter+Brake+Inverter
- Open Emitter configuration
- Tandem diode
- Temperature sensor

flow E1 12 mm housing



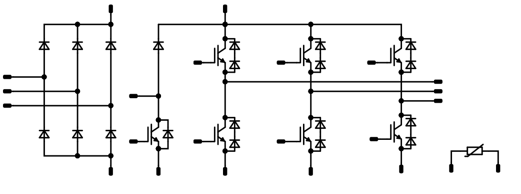
Component features

- Easy paralleling
- Low turn-off losses
- Low collector emitter saturation voltage
- Positive temperature coefficient
- Short tail current
- Switching optimized for EMC

Housing features

- Base isolation: Al_2O_3
- Convex shaped substrate for superior thermal contact
- Compact housing
- CTI600 housing material
- Thermo-mechanical push-and-pull force relief
- Solder pin

Schematic



Target applications

- Embedded Drives
- Industrial Drives

Types

- 10-E112PMA015M701-L928A73Z

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions		Value	Unit
Inverter Switch					
Collector-emitter voltage	V_{CES}			1200	V
Collector current (DC current)	I_C	$T_j = T_{jmax}$	T_s <= 80 °C	30 (1)	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}		30	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	64	W
Gate-emitter voltage	V_{GES}			±20	V
Short circuit ratings	t_{SC}	V_{GE} = 15 V, V_{CC} = 800 V	T_j = 150 °C	9,5	µs
Maximum junction temperature	T_{jmax}			175	°C

(1) limited by I_{CRM}

Parameter	Symbol	Conditions		Value	Unit
Inverter Diode					
Peak repetitive reverse voltage	V_{RRM}			1300	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$	T_s = 80 °C	29	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}		45	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	97	W
Maximum junction temperature	T_{jmax}			175	°C
Brake Switch					
Collector-emitter voltage	V_{CES}			1200	V
Collector current (DC current)	I_C	$T_j = T_{jmax}$	T_s <= 80 °C	30 (2)	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}		30	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	64	W
Gate-emitter voltage	V_{GES}			±20	V
Short circuit ratings	t_{SC}	V_{GE} = 15 V, V_{CC} = 800 V	T_j = 150 °C	9,5	µs
Maximum junction temperature	T_{jmax}			175	°C

(2) limited by I_{CRM}

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions		Value	Unit
Brake Diode					
Peak repetitive reverse voltage	V_{RRM}			1200	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$	T_s <= 80 °C	20 [3]	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}		20	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	43	W
Maximum junction temperature	T_{jmax}			175	°C

[3] limited by I_{FRM}

Parameter	Symbol	Conditions		Value	Unit
Brake Sw. Protection Diode					
Peak repetitive reverse voltage	V_{RRM}			1200	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$	T_s <= 80 °C	10 [4]	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}		10	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	30	W
Maximum junction temperature	T_{jmax}			175	°C

[4] limited by I_{FRM}

Parameter	Symbol	Conditions		Value	Unit
Rectifier Diode					
Peak repetitive reverse voltage	V_{RRM}			1600	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$	T_s = 80 °C	47	A
Surge (non-repetitive) forward current	I_{FSM}	Single Half Sine Wave, t_p = 10 ms	T_j = 150 °C	270	A
Surge current capability	I^2t	Single Half Sine Wave, t_p = 10 ms	T_j = 150 °C	370	A^2s
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	58	W
Maximum junction temperature	T_{jmax}			150	°C

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Module Properties				
Thermal Properties				
Storage temperature	T_{stg}		-40…+125	°C
Operation temperature under switching condition	T_{jop}		-40…+(T_{jmax} - 25)	°C
Isolation Properties				
Isolation voltage	V_{isol}	DC Test Voltage* t_p = 2 s	6000	V
Creepage distance			>12,7	mm
Clearance			>12,7	mm
Comparative Tracking Index	CTI		≥ 600	

*100 % tested in production

Characteristic Values

Parameter	Symbol	Conditions	V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_{F} [V]	I_{C} [A] I_{D} [A] I_{F} [A]	T_{j} [°C]	Min	Typ	Max	Unit
Inverter Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$			10	0,0015	25	5,4	6	6,6	V
Collector-emitter saturation voltage	V_{CEsat}		15		15	25 125 150		1,7 1,95 2,01	2,1(5)	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			60	µA
Gate-emitter leakage current	I_{GES}		20	0		25			200	nA
Internal gate resistance	r_{g}							None		Ω
Input capacitance	C_{ies}		0	10		25		2900		pF
Output capacitance	C_{oes}		0	10		25		120		pF
Reverse transfer capacitance	C_{res}		0	10		25		34		pF
Gate charge	Q_{g}	V_{CC} = 600 V	0/15		15	25		110		nC
Thermal										
Thermal resistance junction to sink(6)	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,48		K/W
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{gon} = 16 Ω R_{goff} = 16 Ω	-5/15	600	15	25 125 150		65,95 63,97 63,17		ns
Rise time	t_{r}	R_{gon} = 16 Ω R_{goff} = 16 Ω	-5/15	600	15	25 125 150		34,86 36,89 37,32		ns
Turn-off delay time	$t_{d(off)}$	R_{gon} = 16 Ω R_{goff} = 16 Ω	-5/15	600	15	25 125 150		170,08 193,53 198,79		ns
Fall time	t_{f}	R_{gon} = 16 Ω R_{goff} = 16 Ω	-5/15	600	15	25 125 150		89,82 117,43 121,76		ns
Turn-on energy (per pulse)	E_{on}	Q_{rFWD}=0,339 µC Q_{rFWD}=0,752 µC Q_{rFWD}=0,872 µC	-5/15	600	15	25 125 150		0,671 0,996 1,08		mWs
Turn-off energy (per pulse)	E_{off}		-5/15	600	15	25 125 150		1 1,31 1,41		mWs

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Inverter Diode										
Static										
Forward voltage	V_F				15	25 125 150		2,91 2,7 2,63	3,84(5)	V
Reverse leakage current	I_R	V_r = 1300 V				25			0,94	µA
Thermal										
Thermal resistance junction to sink(6)	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						0,97		K/W
Dynamic										
Peak recovery current	I_{RM}	di/dt=378 A/µs di/dt=308 A/µs di/dt=342 A/µs	-5/15	600	15	25 125 150		6,24 9,06 9,55		A
Reverse recovery time	t_{rr}					25 125 150		88,11 139,71 154,9		ns
Recovered charge	Q_r					25 125 150		0,339 0,752 0,872		µC
Reverse recovered energy	E_{rec}					25 125 150		0,106 0,241 0,284		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 125 150		214,64 157,75 114,53		A/µs

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Brake Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$			10	0,0015	25	5,4	6	6,6	V
Collector-emitter saturation voltage	V_{CEsat}		15		15	25 125 150		1,7 1,95 2,01	2,1(5)	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			60	µA
Gate-emitter leakage current	I_{GES}		20	0		25			200	nA
Internal gate resistance	r_g							None		Ω
Input capacitance	C_{ies}		0	10		25		2900		pF
Output capacitance	C_{oes}							120		pF
Reverse transfer capacitance	C_{res}							34		pF
Gate charge	Q_g	V_{CC} = 600 V	0/15		15	25		110		nC
Thermal										
Thermal resistance junction to sink(6)	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,48		K/W
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{gon} = 32 Ω R_{goff} = 32 Ω	0/15	600	15	25 125 150		299,8 261,6 252,6		ns
Rise time	t_r					25 125 150		193,8 204,6 209,2		ns
Turn-off delay time	$t_{d(off)}$					25 125 150		387,8 427,8 438,2		ns
Fall time	t_f					25 125 150		66,52 86,69 88,96		ns
Turn-on energy (per pulse)	E_{on}	Q_{rFWD}=1,11 µC Q_{rFWD}=1,78 µC Q_{rFWD}=2,04 µC				25 125 150		2,5 3 3,19		mWs
Turn-off energy (per pulse)	E_{off}					25 125 150		1,12 1,44 1,54		mWs

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Brake Diode										
Static										
Forward voltage	V_F				10	25 125 150		1,61 1,69 1,7	1,9(5)	V
Reverse leakage current	I_R	V_r = 1200 V				25			25	µA
Thermal										
Thermal resistance junction to sink(6)	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						2,19		K/W
Dynamic										
Peak recovery current	I_{RM}	d*i*/d*t*=74 A/µs d*i*/d*t*=65 A/µs d*i*/d*t*=62 A/µs	0/15	600	15	25 125 150		5,91 6,68 6,84		A
Reverse recovery time	t_{rr}					25 125 150		317,36 472,66 542,16		ns
Recovered charge	Q_r					25 125 150		1,11 1,78 2,04		µC
Reverse recovered energy	E_{rec}					25 125 150		0,368 0,644 0,753		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 125 150		40,15 27,59 23,82		A/µs

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_{F} [V]	I_{C} [A] I_{D} [A] I_{F} [A]	T_{j} [°C]	Min	Typ	Max	
Brake Sw. Protection Diode										
Static										
Forward voltage	V_{F}				5	25 125 150		1,57 1,66 1,65	2,1(5)	V
Reverse leakage current	I_{R}	V_{r} = 1200 V				25			20	µA
Thermal										
Thermal resistance junction to sink(6)	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						3,19		K/W
Rectifier Diode										
Static										
Forward voltage	V_{F}				13	25 125		0,988 0,899	1,21(5) 1,1(5)	V
Reverse leakage current	I_{R}	V_{r} = 1600 V				25			50	µA
Thermal										
Thermal resistance junction to sink(6)	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,2		K/W
Thermistor										
Static										
Rated resistance	R					25		5		kΩ
Deviation of R100	$\Delta_{R/R}$	R_{100} = 499 Ω				100	3,2		3,3	%
Power dissipation	P					25		130		mW
Power dissipation constant	d					25		1,3		mW/K
B-value	$B_{(25/50)}$	Tol. ±1 %						3380		K
Vincotech Thermistor Reference									V	

(5) Value at chip level

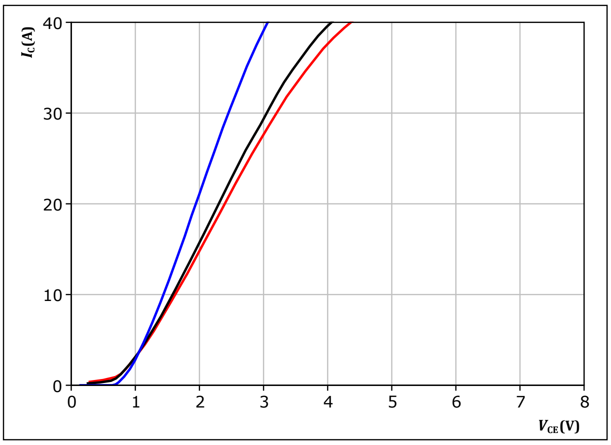
(6) Only valid with pre-applied Vincotech thermal interface material.

Inverter Switch Characteristics

figure 1. **IGBT**

Typical output characteristics

I_C = f(V_{CE})

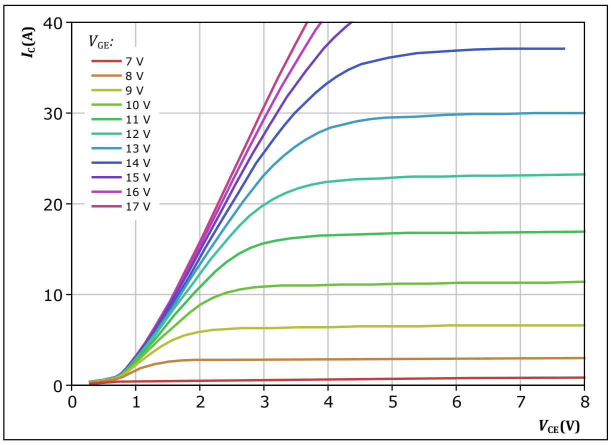


t_p = 250 µs
V_{GE} = 15 V
T_j: 25 °C, 125 °C, 150 °C

figure 2. **IGBT**

Typical output characteristics

I_C = f(V_{CE})

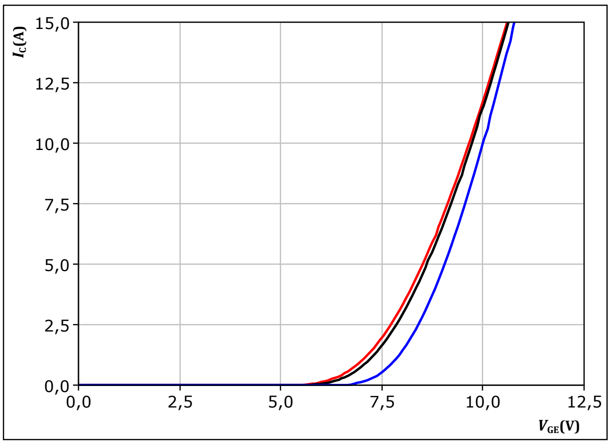


t_p = 250 µs
T_j = 150 °C
V_{GE} from 7 V to 17 V in steps of 1 V

figure 3. **IGBT**

Typical transfer characteristics

I_C = f(V_{GE})

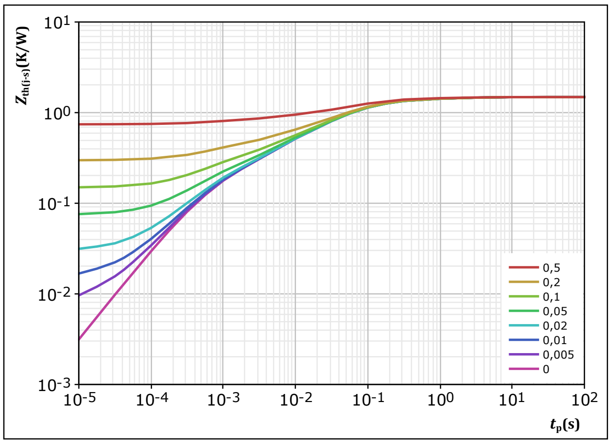


t_p = 250 µs
V_{CE} = 10 V
T_j: 25 °C, 125 °C, 150 °C

figure 4. **IGBT**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)}$ = f(t_p)



D = t_p / T
$R_{th(j-s)}$ = 1,485 K/W

IGBT thermal model values

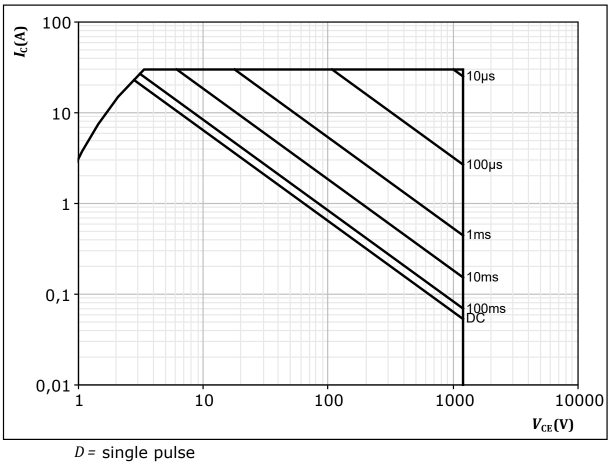
R (K/W)	τ (s)
4,90E-02	3,61E+00
1,10E-01	6,54E-01
4,70E-01	1,09E-01
4,98E-01	2,97E-02
2,21E-01	4,73E-03
1,37E-01	5,51E-04

Inverter Switch Characteristics

figure 5. **IGBT**

Safe operating area

I_C = f(V_{CE})

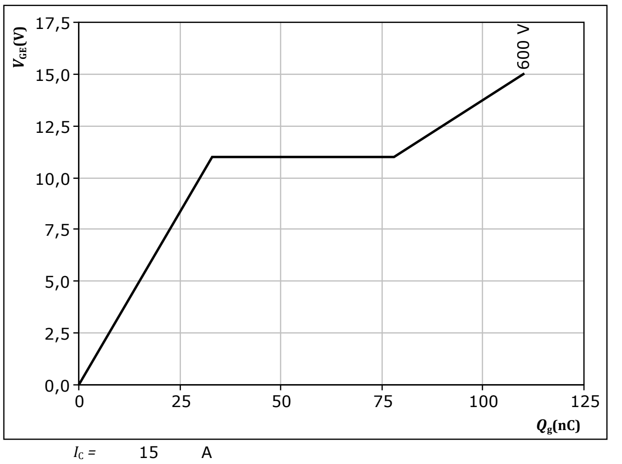


D = single pulse
T_s = 80 °C
V_{GE} = 15 V
T_j = T_{jmax}

figure 6. **IGBT**

Gate voltage vs gate charge

V_{GE} = f(Q_g)



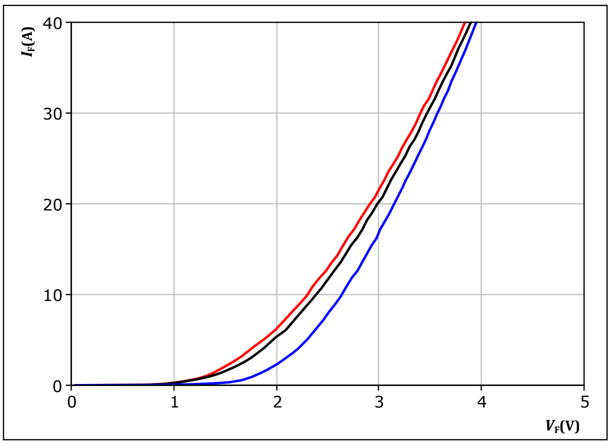
I_C = 15 A
T_j = 25 °C

Inverter Diode Characteristics

figure 7. **FWD**

Typical forward characteristics

I_F = f(V_F)



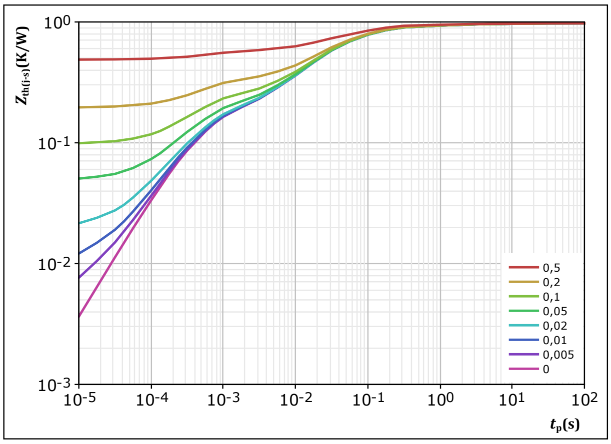
t_p = 250 µs

T_j: 25 °C, 125 °C, 150 °C

figure 8. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)}$ = f(t_p)



D = t_p / T

$R_{th(j-s)}$ = 0,974 K/W

FWD thermal model values

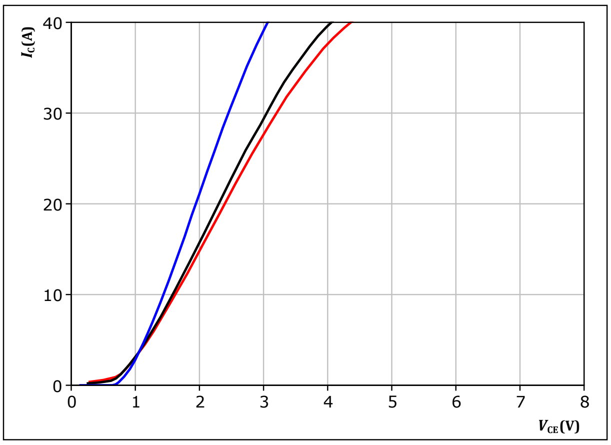
R (K/W)	τ (s)
2,25E-02	9,54E+00
6,00E-02	9,21E-01
3,80E-01	8,25E-02
3,56E-01	1,67E-02
1,56E-01	4,56E-04

Brake Switch Characteristics

figure 9. **IGBT**

Typical output characteristics

I_C = f(V_{CE})



t_p = 250 µs

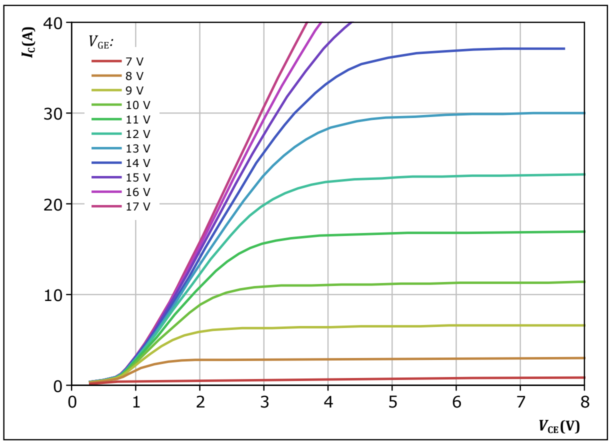
V_{GE} = 15 V

T_j: 25 °C, 125 °C, 150 °C

figure 10. **IGBT**

Typical output characteristics

I_C = f(V_{CE})



t_p = 250 µs

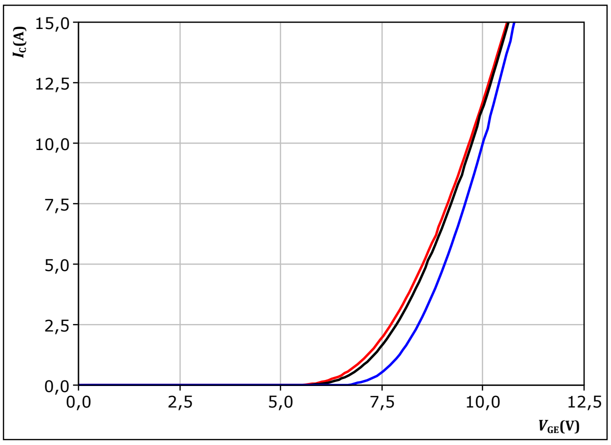
T_j = 150 °C

V_{GE} from 7 V to 17 V in steps of 1 V

figure 11. **IGBT**

Typical transfer characteristics

I_C = f(V_{GE})



t_p = 250 µs

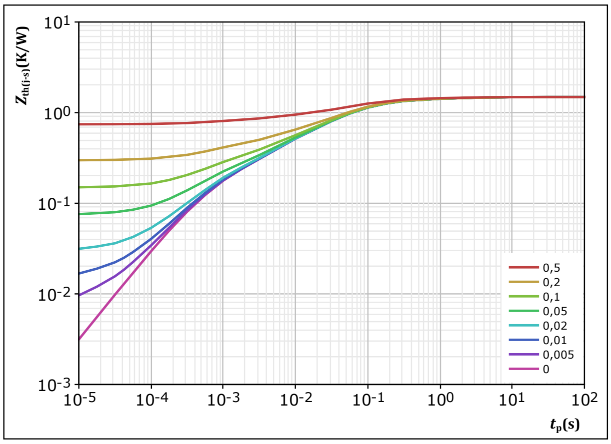
V_{CE} = 10 V

T_j: 25 °C, 125 °C, 150 °C

figure 12. **IGBT**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)}$ = f(t_p)



D = t_p / T

$R_{th(j-s)}$ = 1,485 K/W

IGBT thermal model values

R (K/W)	τ (s)
4,90E-02	3,61E+00
1,10E-01	6,54E-01
4,70E-01	1,09E-01
4,98E-01	2,97E-02
2,21E-01	4,73E-03
1,37E-01	5,51E-04

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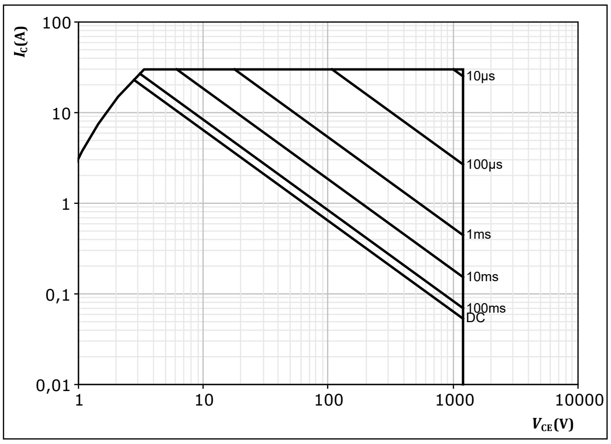
Brake Switch Characteristics

figure 13. **IGBT**

Safe operating area

I_C = f(V_{CE})

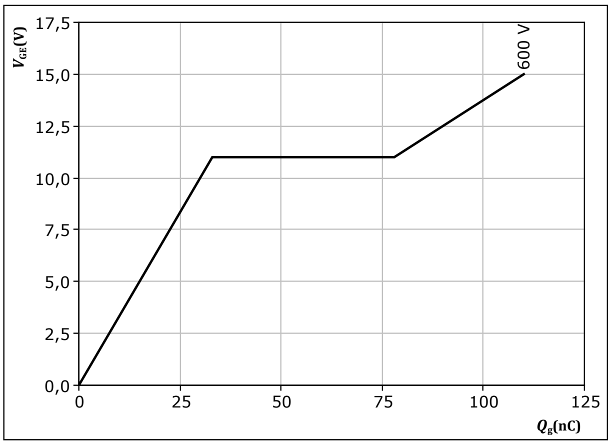


D =	single pulse	
T_s =	80	°C
V_{GE} =	15	V
T_j =	T_{jmax}	

figure 14. **IGBT**

Gate voltage vs gate charge

V_{GE} = f(Q_g)



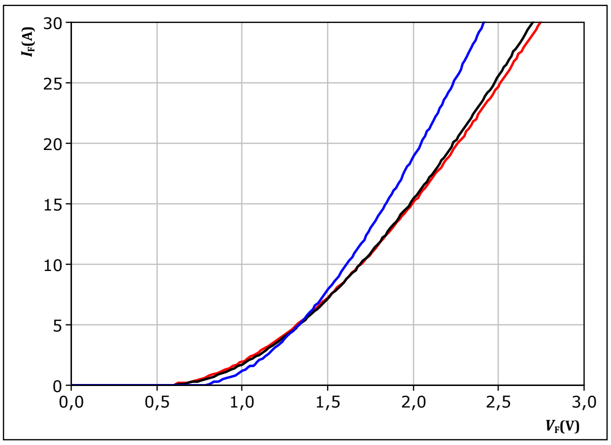
I_C =	15	A
T_j =	25	°C

Brake Diode Characteristics

figure 15. **FWD**

Typical forward characteristics

$I_F = f(V_F)$



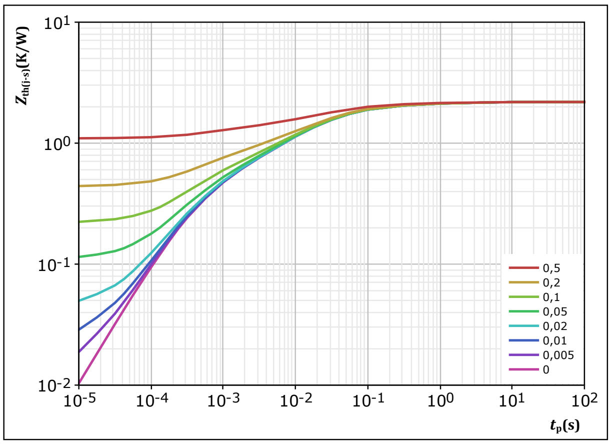
t_p = 250 µs

T_j: 25 °C, 125 °C, 150 °C

figure 16. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



D = t_p / T

$R_{th(j-s)}$ = 2,189 K/W

FWD thermal model values

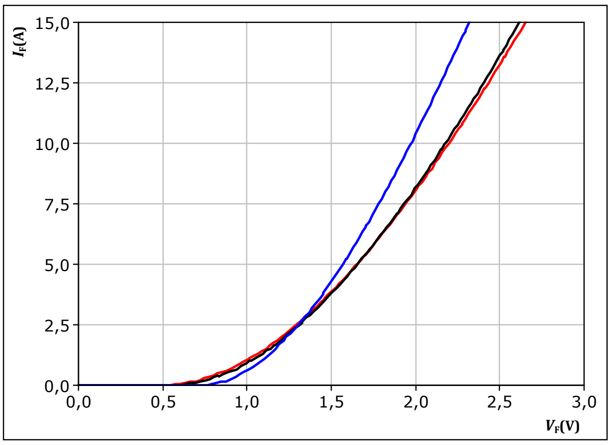
R (K/W)	τ (s)
8,09E-02	3,20E+00
2,08E-01	2,82E-01
6,85E-01	4,41E-02
5,92E-01	1,02E-02
3,27E-01	2,02E-03
2,95E-01	3,64E-04

Brake Sw. Protection Diode Characteristics

figure 17. FWD

Typical forward characteristics

$I_F = f(V_F)$



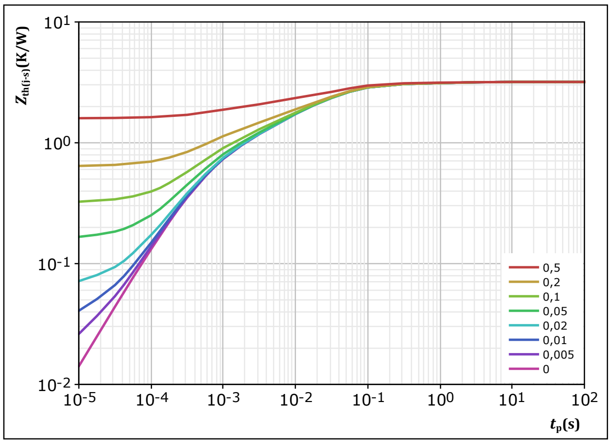
t_p = 250 µs

T_j: 25 °C, 125 °C, 150 °C

figure 18. FWD

Transient thermal impedance as a function of pulse width

$Z_{th(j\text{-}s)} = f(t_p)$



$D = t_p / T$

$R_{th(j\text{-}s)}$ = 3,189 K/W

FWD thermal model values

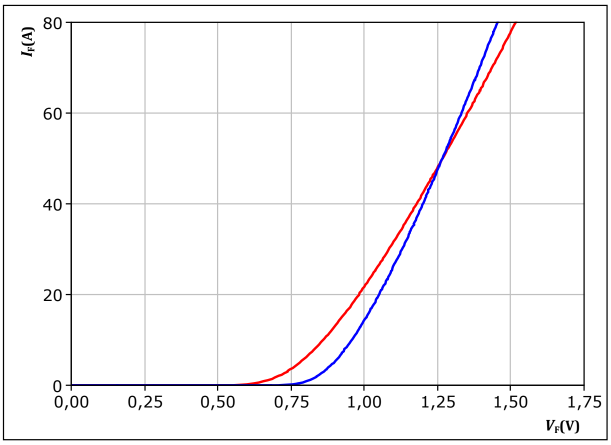
R (K/W)	τ (s)
1,13E-01	1,88E+00
4,09E-01	1,23E-01
1,37E+00	2,62E-02
7,40E-01	3,25E-03
5,56E-01	4,86E-04

Rectifier Diode Characteristics

figure 19. **Rectifier**

Typical forward characteristics

$I_F = f(V_F)$



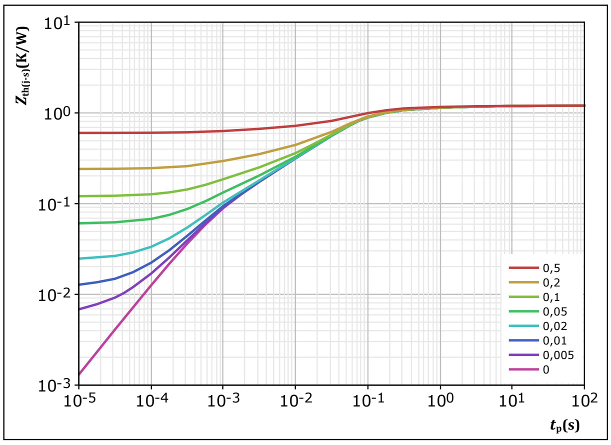
t_p = 250 µs

T_j: 25 °C, 125 °C

figure 20. **Rectifier**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



$D = t_p / T$

$R_{th(j-s)}$ = 1,202 K/W

Rectifier thermal model values

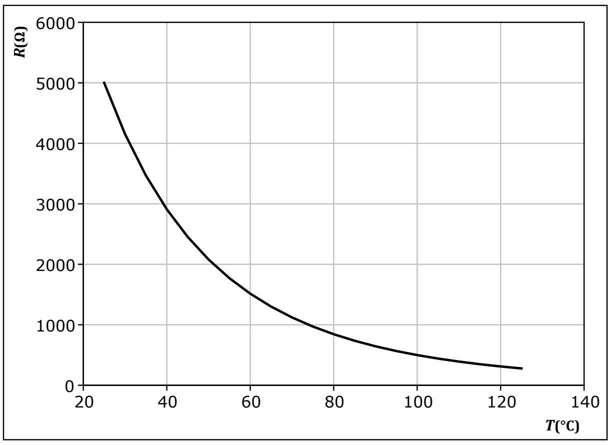
R (K/W)	τ (s)
3,54E-02	9,31E+00
8,09E-02	9,99E-01
2,12E-01	1,71E-01
6,76E-01	4,85E-02
1,19E-01	5,88E-03
7,98E-02	8,33E-04

Thermistor Characteristics

figure 21.	Thermistor

Typical NTC characteristic as function of temperature

$R_T = f(T)$

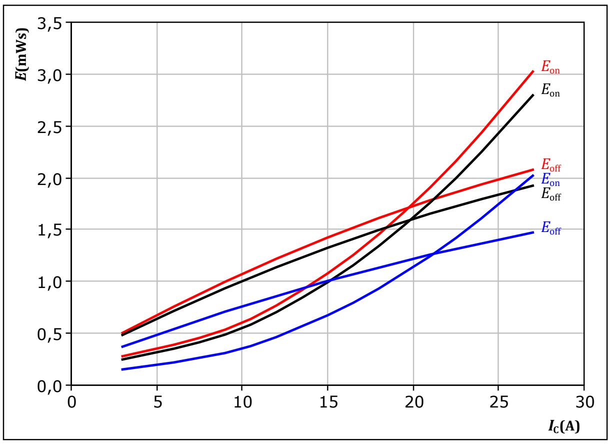


Inverter Switching Characteristics

figure 22. **IGBT**

Typical switching energy losses as a function of collector current

E = f(I_C)



With an inductive load at

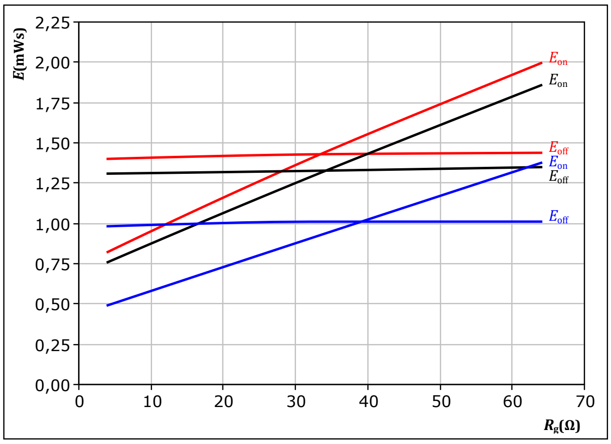
V_{CE} =	600	V	
V_{GE} =	-5/15	V	
R_{gon} =	16	Ω	
R_{goff} =	16	Ω	

T_j: 25 °C, 125 °C, 150 °C

figure 23. **IGBT**

Typical switching energy losses as a function of IGBT turn on gate resistor

E = f(R_g)



With an inductive load at

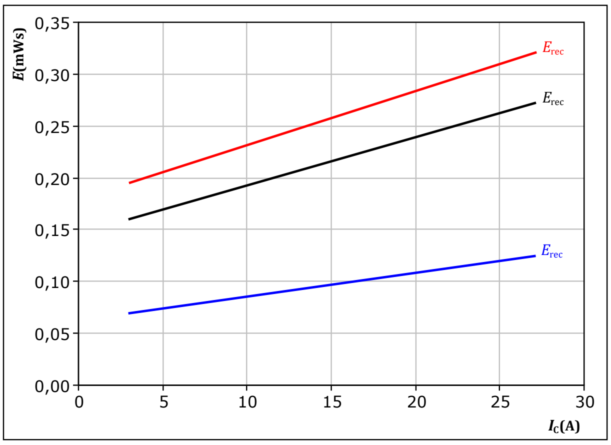
V_{CE} =	600	V
V_{GE} =	-5/15	V
I_C =	15	A

T_j: 25 °C, 125 °C, 150 °C

figure 24. **FWD**

Typical reverse recovered energy loss as a function of collector current

E_{rec} = f(I_C)



With an inductive load at

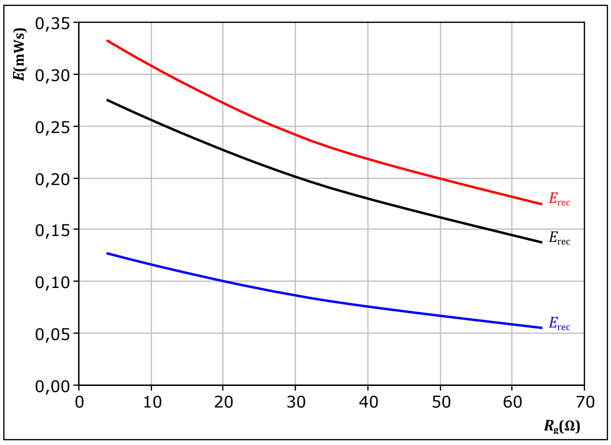
V_{CE} =	600	V
V_{GE} =	-5/15	V
R_{gon} =	16	Ω

T_j: 25 °C, 125 °C, 150 °C

figure 25. **FWD**

Typical reverse recovered energy loss as a function of IGBT turn on gate resistor

E_{rec} = f(R_g)



With an inductive load at

V_{CE} =	600	V
V_{GE} =	-5/15	V
I_C =	15	A

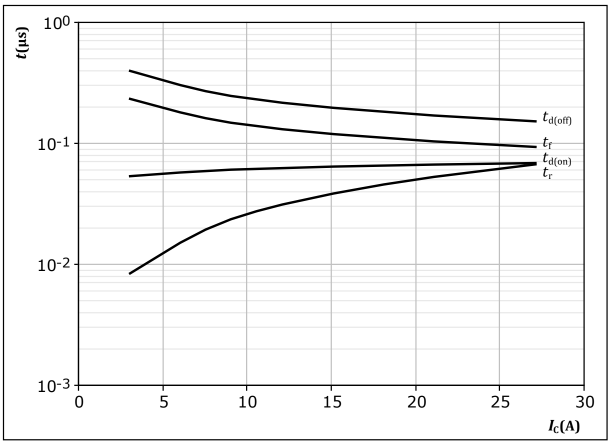
T_j: 25 °C, 125 °C, 150 °C

Inverter Switching Characteristics

figure 26. IGBT

Typical switching times as a function of collector current

t = f(I_C)



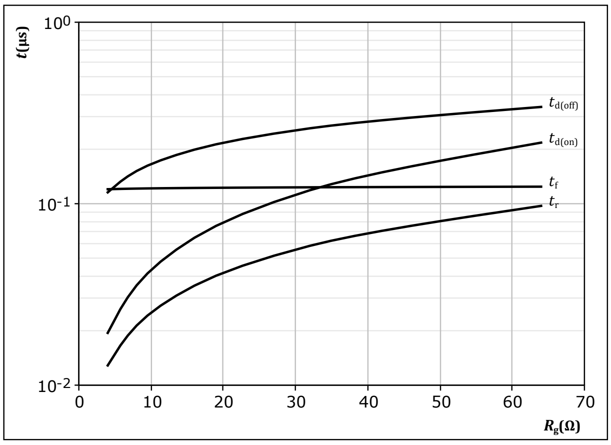
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	-5/15	V
R_{gon} =	16	Ω
R_{goff} =	16	Ω

figure 27. IGBT

Typical switching times as a function of IGBT turn on gate resistor

t = f(R_g)



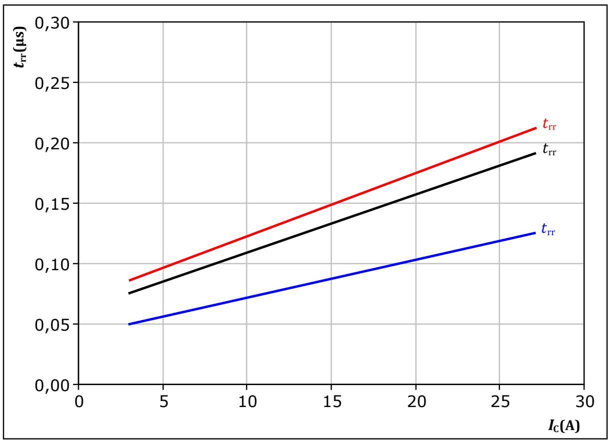
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	-5/15	V
I_C =	15	A

figure 28. FWD

Typical reverse recovery time as a function of collector current

t_{rr} = f(I_C)



With an inductive load at

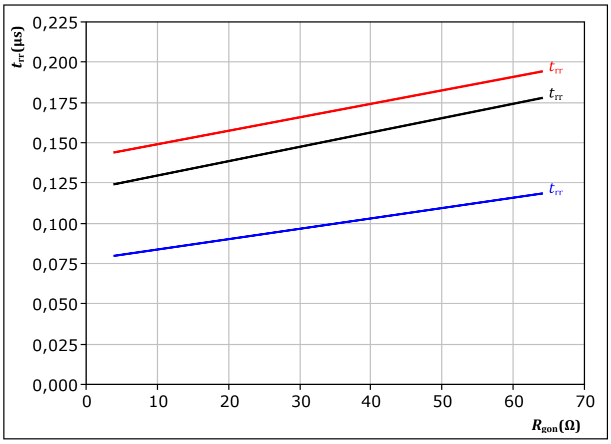
V_{CE} =	600	V
V_{GE} =	-5/15	V
R_{gon} =	16	Ω

T_j: 25 °C, 125 °C, 150 °C

figure 29. FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor

t_{rr} = f(R_{gon})



With an inductive load at

V_{CE} =	600	V
V_{GE} =	-5/15	V
I_C =	15	A

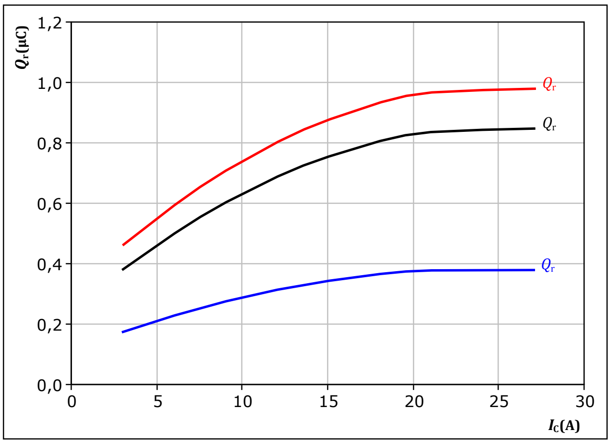
T_j: 25 °C, 125 °C, 150 °C

Inverter Switching Characteristics

figure 30. **FWD**

Typical recovered charge as a function of collector current

Q_r = f(I_C)



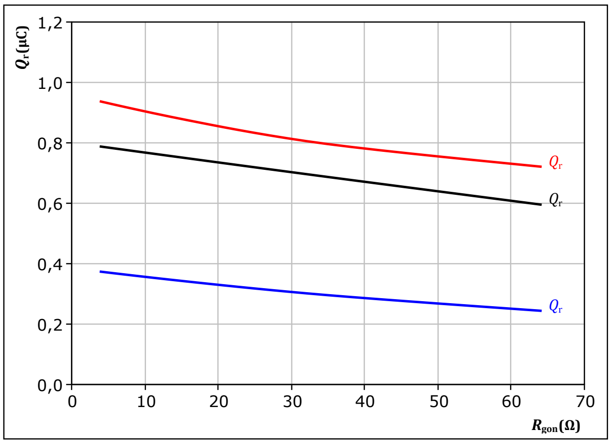
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	-5/15	V		125 °C
R_{gon} =	16	Ω		150 °C

figure 31. **FWD**

Typical recovered charge as a function of IGBT turn on gate resistor

Q_r = f(R_{gon})



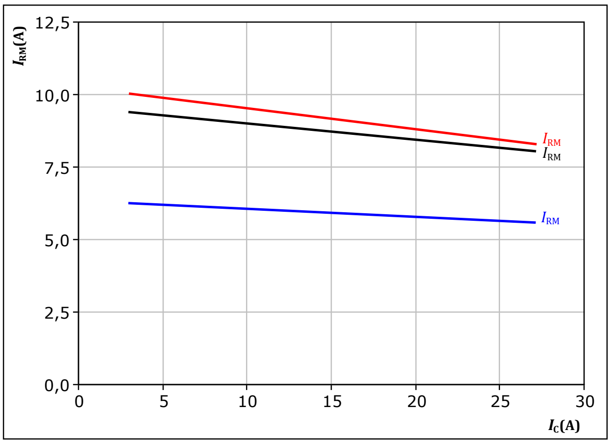
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	-5/15	V		125 °C
I_C =	15	A		150 °C

figure 32. **FWD**

Typical peak reverse recovery current as a function of collector current

I_{RM} = f(I_C)



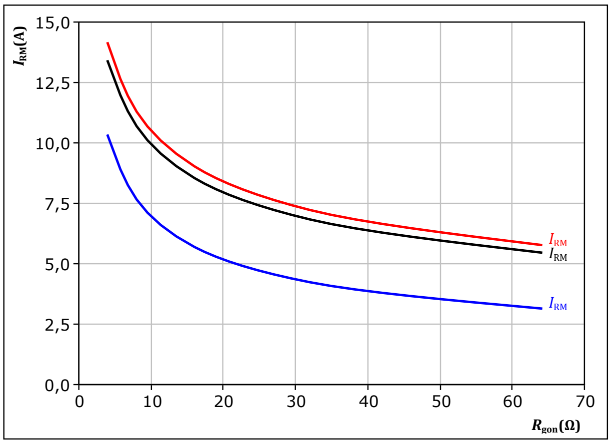
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	-5/15	V		125 °C
R_{gon} =	16	Ω		150 °C

figure 33. **FWD**

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

I_{RM} = f(R_{gon})



With an inductive load at

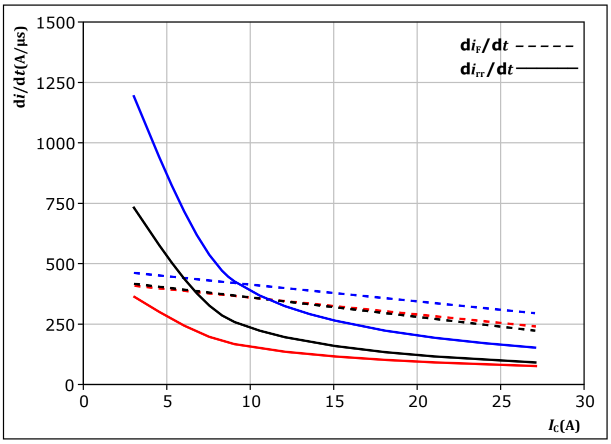
V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	-5/15	V		125 °C
I_C =	15	A		150 °C

Inverter Switching Characteristics

figure 34. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of collector current

di_F/dt, di_{rr}/dt = f(I_C)



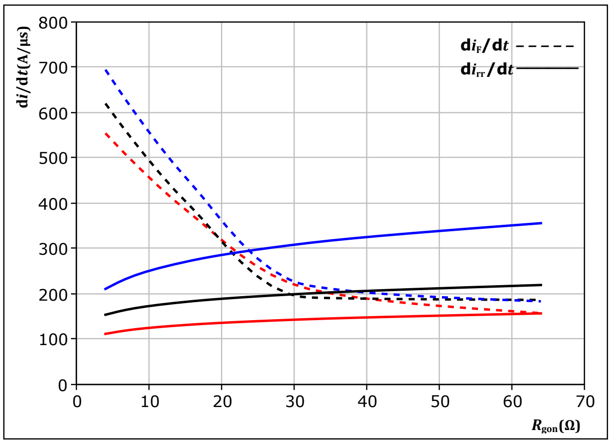
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	-5/15	V		125 °C
R_{gon} =	16	Ω		150 °C

figure 35. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of turn on gate resistor

di_F/dt, di_{rr}/dt = f(R_{gon})



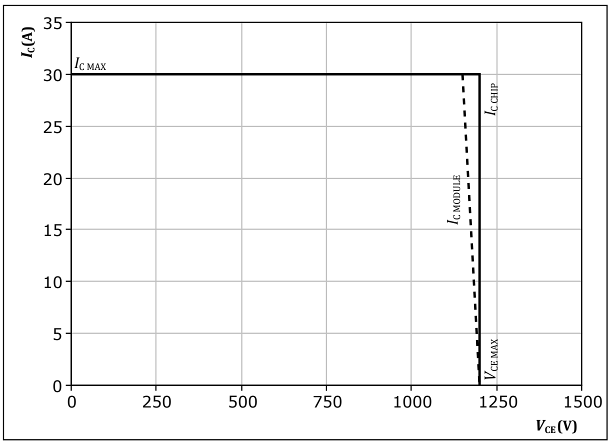
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	-5/15	V		125 °C
I_C =	15	A		150 °C

figure 36. **IGBT**

Reverse bias safe operating area

I_C = f(V_{CE})



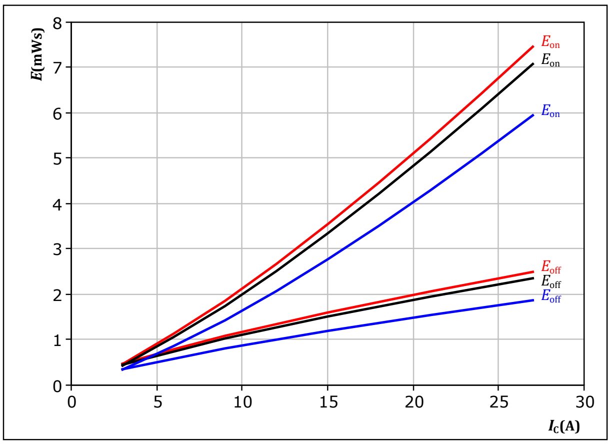
At	T_j =	150	°C
	R_{gon} =	16	Ω
	R_{goff} =	16	Ω

Brake Switching Characteristics

figure 37. **IGBT**

Typical switching energy losses as a function of collector current

$E = f(I_C)$



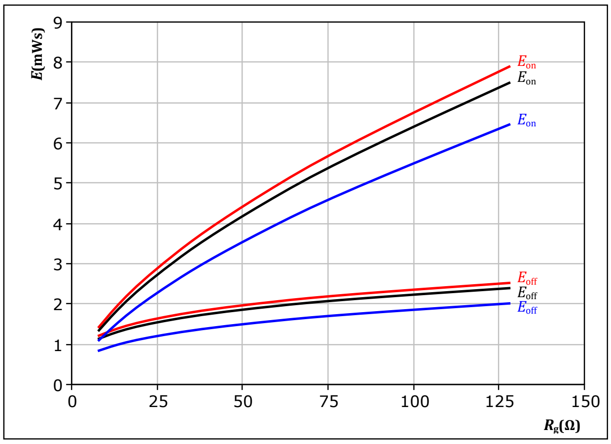
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	0/15	V		125 °C
R_{gon} =	32	Ω		150 °C
R_{goff} =	32	Ω		

figure 38. **IGBT**

Typical switching energy losses as a function of IGBT turn on gate resistor

$E = f(R_g)$



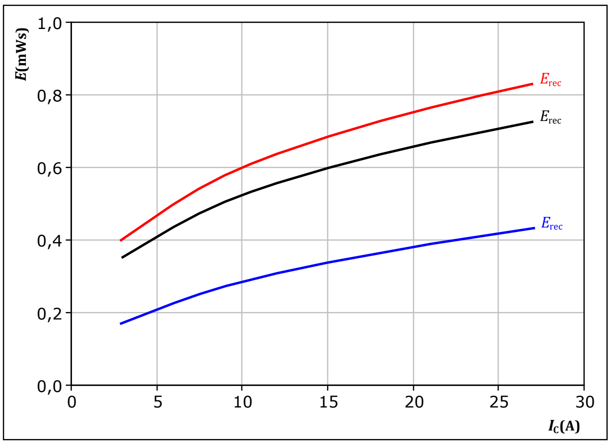
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	0/15	V		125 °C
I_C =	15	A		150 °C

figure 39. **FWD**

Typical reverse recovered energy loss as a function of collector current

$E_{rec} = f(I_C)$



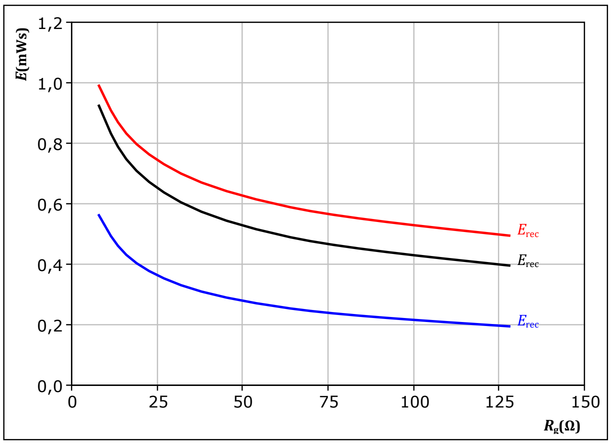
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	0/15	V		125 °C
R_{gon} =	32	Ω		150 °C

figure 40. **FWD**

Typical reverse recovered energy loss as a function of IGBT turn on gate resistor

$E_{rec} = f(R_g)$



With an inductive load at

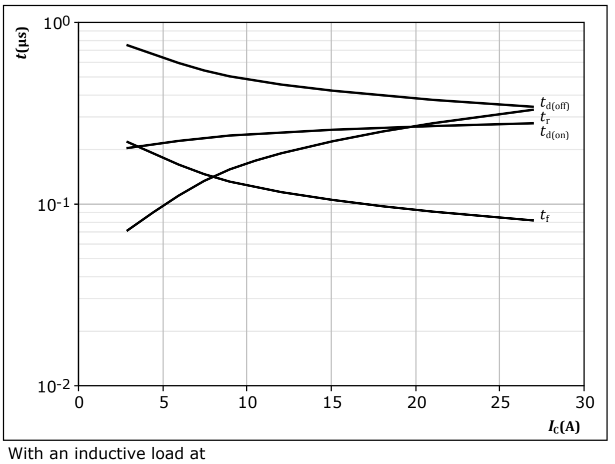
V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	0/15	V		125 °C
I_C =	15	A		150 °C

Brake Switching Characteristics

figure 41. **IGBT**

Typical switching times as a function of collector current

$t = f(I_C)$



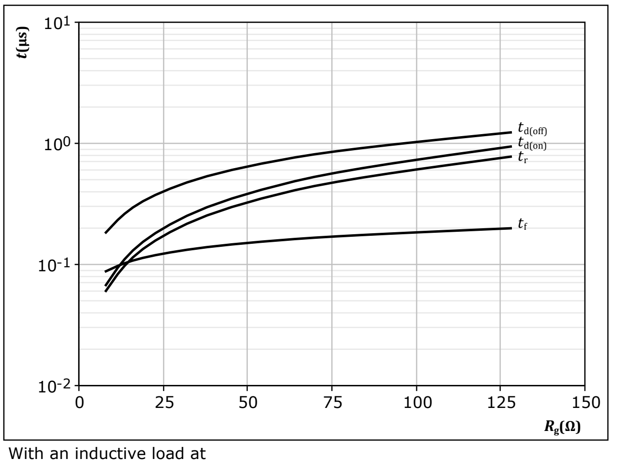
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	0/15	V
R_{gon} =	32	Ω
R_{goff} =	32	Ω

figure 42. **IGBT**

Typical switching times as a function of IGBT turn on gate resistor

$t = f(R_g)$



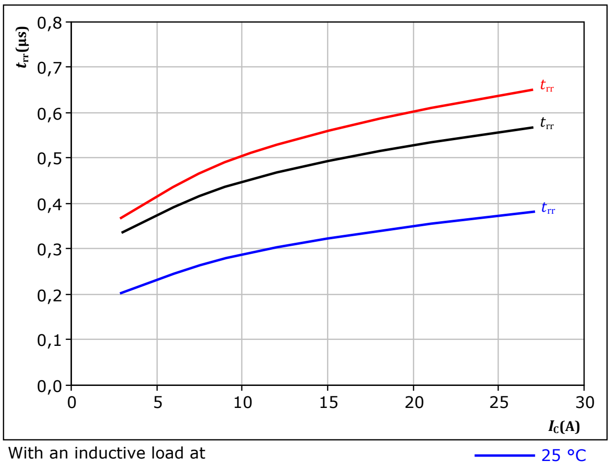
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	0/15	V
I_C =	15	A

figure 43. **FWD**

Typical reverse recovery time as a function of collector current

$t_{rr} = f(I_C)$



With an inductive load at

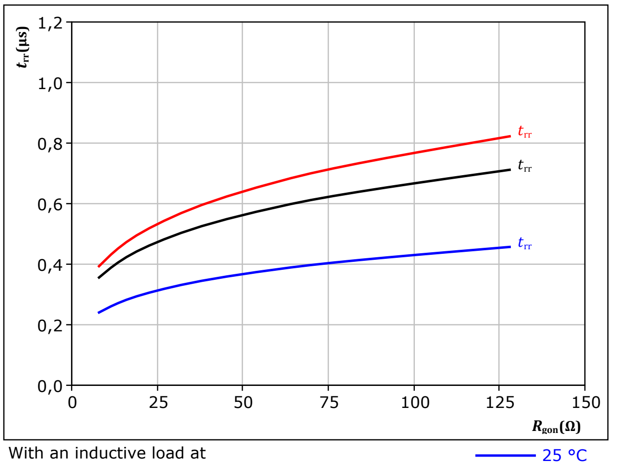
V_{CE} =	600	V
V_{GE} =	0/15	V
R_{gon} =	32	Ω

T_j: 25 °C, 125 °C, 150 °C

figure 44. **FWD**

Typical reverse recovery time as a function of IGBT turn on gate resistor

$t_{rr} = f(R_{gon})$



With an inductive load at

V_{CE} =	600	V
V_{GE} =	0/15	V
I_C =	15	A

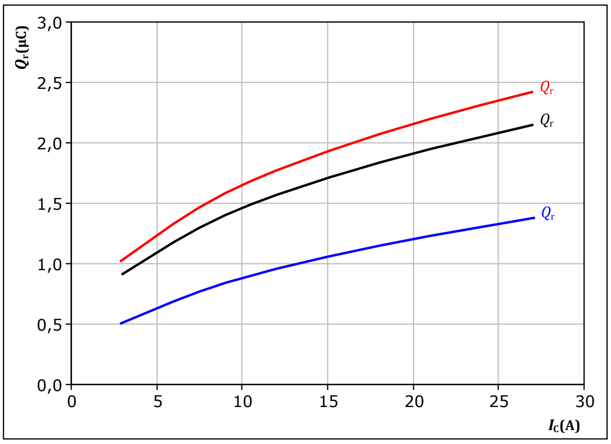
T_j: 25 °C, 125 °C, 150 °C

Brake Switching Characteristics

figure 45. **FWD**

Typical recovered charge as a function of collector current

Q_r = f(I_C)



With an inductive load at

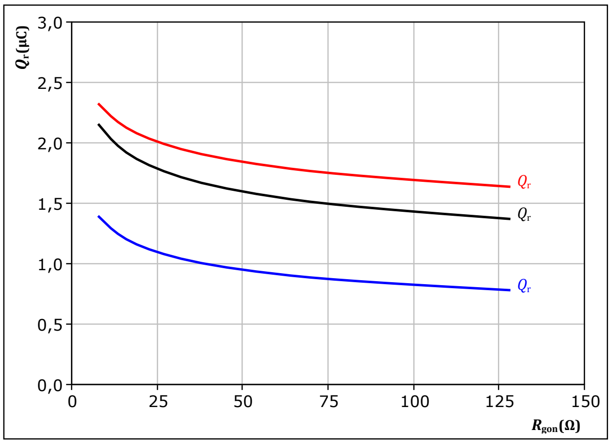
V_{CE} =	600	V	
V_{GE} =	0/15	V	
R_{gon} =	32	Ω	

T_j: 25 °C, 125 °C, 150 °C

figure 46. **FWD**

Typical recovered charge as a function of IGBT turn on gate resistor

Q_r = f(R_{gon})



With an inductive load at

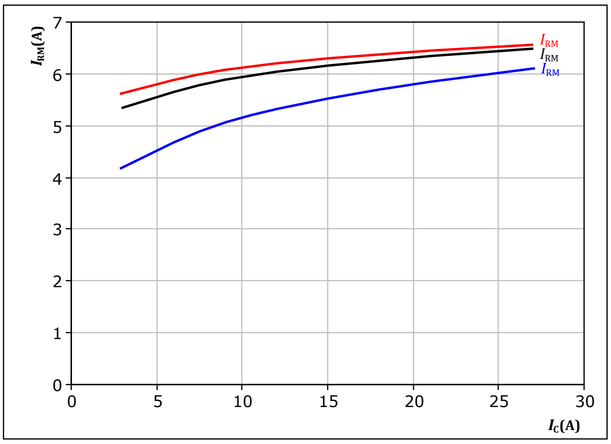
V_{CE} =	600	V	
V_{GE} =	0/15	V	
I_C =	15	A	

T_j: 25 °C, 125 °C, 150 °C

figure 47. **FWD**

Typical peak reverse recovery current as a function of collector current

I_{RM} = f(I_C)



With an inductive load at

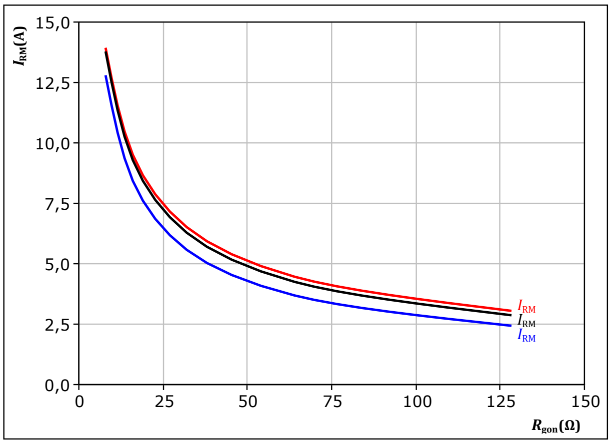
V_{CE} =	600	V	
V_{GE} =	0/15	V	
R_{gon} =	32	Ω	

T_j: 25 °C, 125 °C, 150 °C

figure 48. **FWD**

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

I_{RM} = f(R_{gon})



With an inductive load at

V_{CE} =	600	V	
V_{GE} =	0/15	V	
I_C =	15	A	

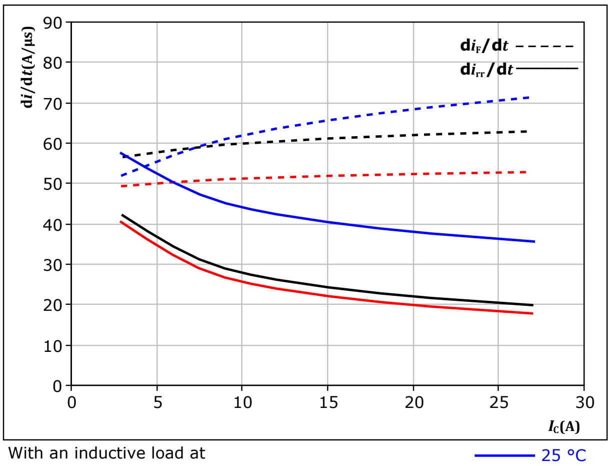
T_j: 25 °C, 125 °C, 150 °C

Brake Switching Characteristics

figure 49. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of collector current

di_F/dt, di_{rr}/dt = f(I_C)



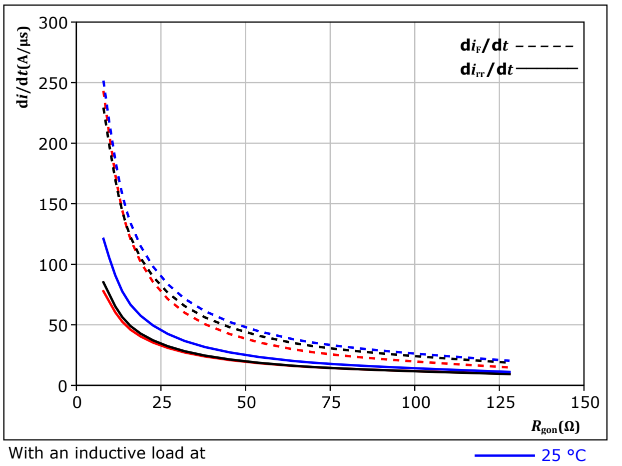
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	0/15	V		125 °C
R_{gon} =	32	Ω		150 °C

figure 50. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of turn on gate resistor

di_F/dt, di_{rr}/dt = f(R_{gon})



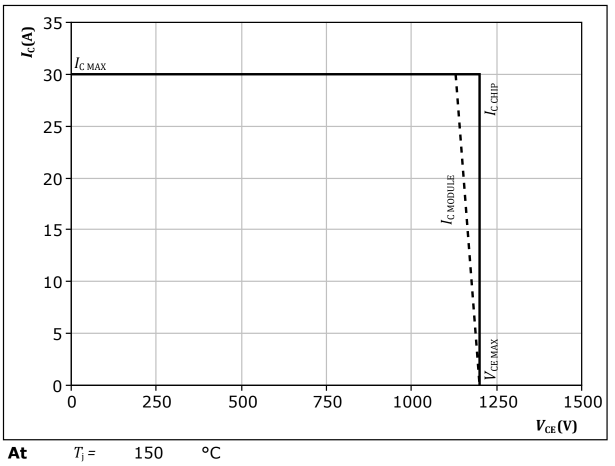
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	0/15	V		125 °C
I_C =	15	A		150 °C

figure 51. **IGBT**

Reverse bias safe operating area

I_C = f(V_{CE})



At	T_j =	150	°C
	R_{gon} =	32	Ω
	R_{goff} =	32	Ω

Switching Definitions

figure 52. **IGBT**

Turn-off Switching Waveforms & definition of t_{doff}, t_{Eoff} (t_{tEoff} **= integrating time for** E_{off})

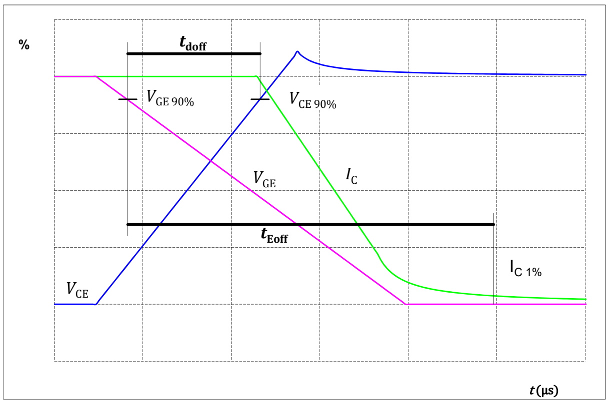


figure 53. **IGBT**

Turn-on Switching Waveforms & definition of t_{don}, t_{Eon} (t_{Eon} **= integrating time for** E_{on})

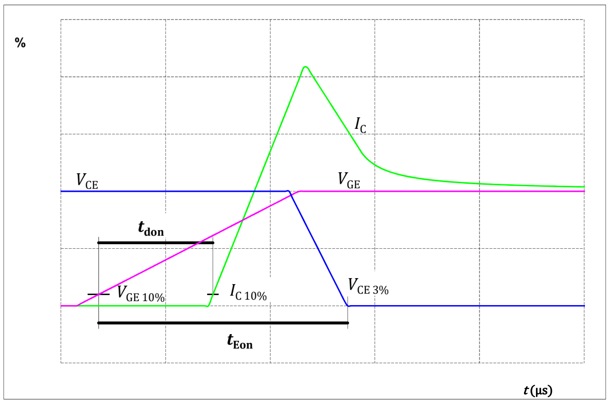


figure 54. **IGBT**

Turn-off Switching Waveforms & definition of t_f

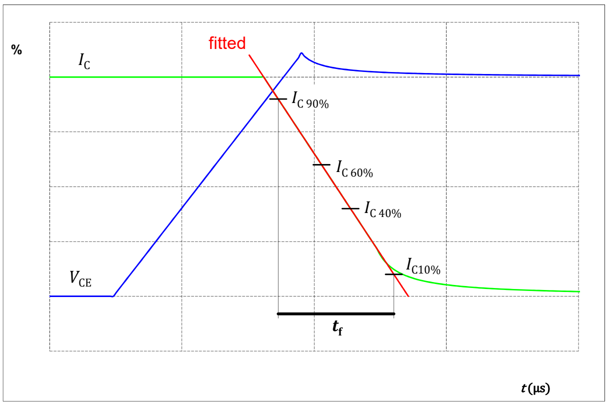
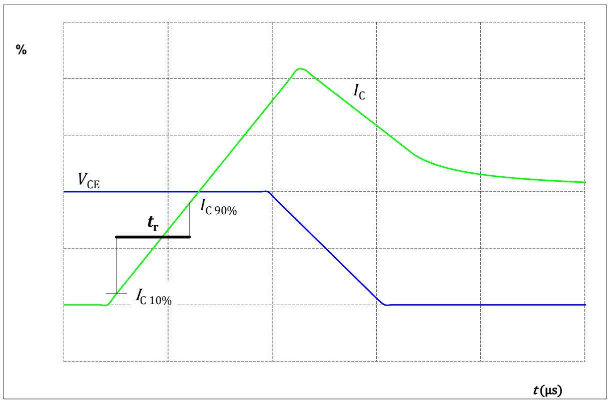


figure 55. **IGBT**

Turn-on Switching Waveforms & definition of t_r



Switching Definitions

figure 56.	FWD

Turn-off Switching Waveforms & definition of t_{rr}

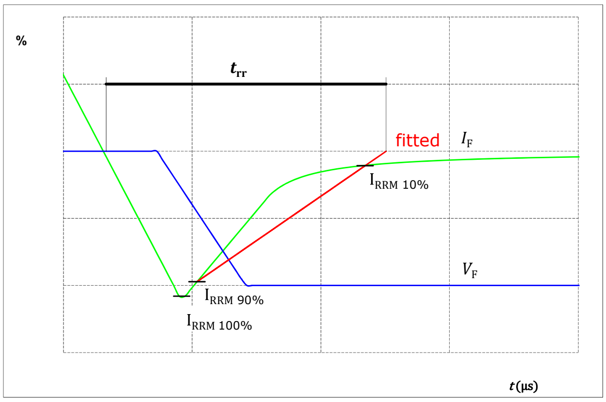
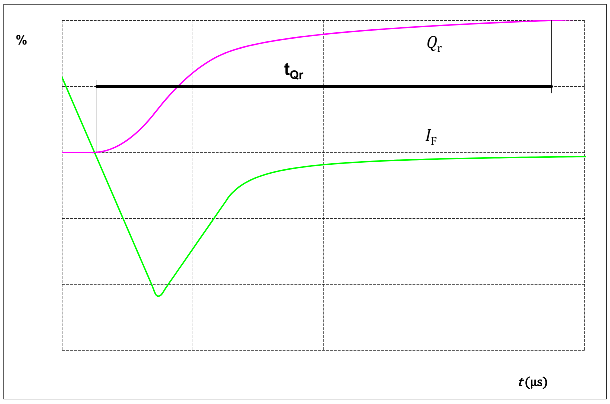


figure 57.	FWD

Turn-on Switching Waveforms & definition of t_{Qr} **(**t_{Qr} **= integrating time for** Q_r**)**



Ordering Code

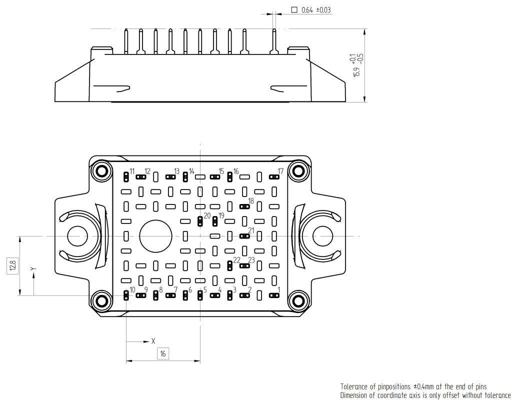
Version	Ordering Code
Without thermal paste	10-E112PMA015M701-L928A73Z
With thermal paste (3,4 W/mK, PSX-P7)	10-E112PMA015M701-L928A73Z-/3/

Marking

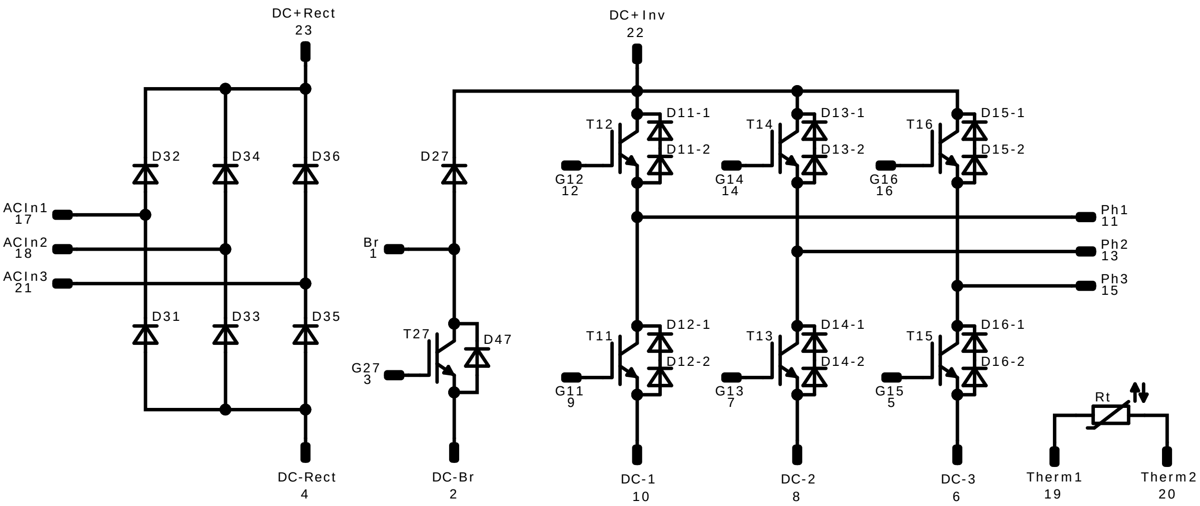
Text	Name		Date code	UL & VIN	Lot	Serial
	NN-NNNNNNNNNNNNNN-TTTTTTVV		WWYY	UL VIN	LLLLL	SSSS
Datamatrix	Type&Ver	Lot number	Serial	Date code		
	TTTTTTTVV	LLLLL	SSSS	WWYY		

Outline

Pin table [mm]			
Pin	X	Y	Function
1	32	0	Br
2	25,6	0	DC-Br
3	22,4	0	G27
4	19,2	0	DC-Rect
5	16	0	G15
6	12,8	0	DC-3
7	9,6	0	G13
8	6,4	0	DC-2
9	3,2	0	G11
10	0	0	DC-1
11	0	25,6	Ph1
12	3,2	25,6	G12
13	9,6	25,6	Ph2
14	12,8	25,6	G14
15	19,2	25,6	Ph3
16	22,4	25,6	G16
17	32	25,6	ACIn1
18	25,6	19,2	ACIn2
19	19,2	16	Therm1
20	16	16	Therm2
21	25,6	12,8	ACIn3
22	22,4	6,4	DC+Inv
23	25,6	6,4	DC+Rect



Pinout



Identification

ID	Component	Voltage	Current	Function	Comment
T11, T12, T13, T14, T15, T16	IGBT	1200 V	15 A	Inverter Switch	
D11-1, D11-2, D12-1, D12-2, D13-1, D13-2, D14-1, D14-2, D15-1, D15-2, D16-1, D16-2	FWD	1300 V	15 A	Inverter Diode	
T27	IGBT	1200 V	15 A	Brake Switch	
D27	FWD	1200 V	10 A	Brake Diode	
D47	FWD	1200 V	5 A	Brake Sw. Protection Diode	
D31, D32, D33, D34, D35, D36	Rectifier	1600 V	35 A	Rectifier Diode	
Rt	Thermistor			Thermistor	

Packaging instruction				
Standard packaging quantity (SPQ) 100	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for *flow* E1 packages see vincotech.com website.

Package data
Package data for *flow* E1 packages see vincotech.com website.

Vincotech thermistor reference
See Vincotech thermistor reference table at vincotech.com website.

UL recognition and file number
This device is UL 1557 recognized under E192116 up to a junction temperature under switching condition $T_{j,op}$=175°C and up to 3500VAC/1min isolation voltage. For more information see vincotech.com website.

Document No.:	Date:	Modification:	Pages
10-E112PMA015M701-L928A73Z-D1-14	16 Aug. 2023		
10-E112PMA015M701-L928A73Z-D2-14	23 Feb. 2024	Updated dynamic characteristic	

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.